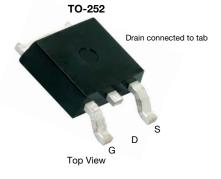
Vishay Siliconix



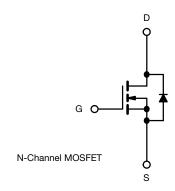
PRODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a		
30	0.0120 at V _{GS} = 10 V	16.8		
	0.0175 at V _{GS} = 4.5 V	13.9		



FEATURES

- TrenchFET[®] power MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>





Ordering Information:

SUD50N03-12P-GE3 (lead (Pb)-free and halogen-free)

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage		V _{DS}	30	V		
Gate-Source Voltage		V _{GS}	± 20	V		
Continuous Drain Current ^a	T _A = 25 °C		16.8			
Continuous Drain Current "	T _A = 100 °C		10.6			
Pulsed Drain Current	I _{DM}	40	А			
Continuous Source Current (Diode Conduction) ^a	I _S	3.6				
Avalanche Current	L = 0.1 mH	I _{AS}	30			
Single Pulse Avalanche Energy	L = 0.1 MH	E _{AS}	45	mJ		
Marine Paula Diasia stian	T _C = 25 °C	T _C = 25 °C		w		
Maximum Power Dissipation	T _A = 25 °C	P _D	5.4 ^a	V		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum Junction-to-Ambient ^a	t ≤ 10 s	R _{thJA}	18	23	°C/W	
	Steady State		40	50		
Maximum Junction-to-Case		R _{thJC}	2.6	3.2		

Note

a. Surface mounted on FR4 board, t \leq 10 s.

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SUD50N03-12P-GE3



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP. ^a	MAX.	UNIT	
Static			•	•			
Drain-Source Breakdown Voltage	V _{DS}	V_{DS} $V_{GS} = 0 V$, $I_D = 250 \mu A$		-	-	V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},\ I_{D}=250\ \mu A$	1	-	3	v	
Gate-Body Leakage	I _{GSS}	$V_{DS}=0~V,~V_{GS}=\pm~20~V$	-	-	± 100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μΑ	
Zero Gale voltage Drain Current	I _{DSS}	V_{DS} = 24 V, V_{GS} = 0 V, T_J = 125 °C	-	-	50		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 V, V_{GS} = 10 V$	40	-	-	А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$	-	0.0100	0.0120		
Drain-Source On-State Resistance ^b	R _{DS(on)}	V_{GS} = 10 V, I_{D} = 20 A, T_{J} = 125 °C	-	-	0.0170	Ω	
		V_{GS} = 4.5 V, I _D = 15 A	-	0.0138	0.0175		
Forward Transconductance b	g _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 20 \text{ A}$	15	-	-	S	
Dynamic ^a			•	•			
Input Capacitance	C _{iss}		-	1600	-	pF	
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	-	285	-		
Reverse Transfer Capacitance	C _{rss}		-	140	-		
Total Gate Charge ^c	Qg		-	28	42		
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 15 V, V_{GS} = 10 V, I_{D} = 50 A	-	6	-	nC	
Gate-Drain Charge ^c	Q _{gd}		-	5	-		
Gate Resistance	Rg	f = 1 MHz	0.3	1.5	3.0	Ω	
Turn-On Delay Time ^c	t _{d(on)}		-	9	15		
Rise Time ^c	t _r	V_{DD} = 15 V, R_L = 0.3 Ω	-	15	25		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 50$ Å, $V_{GEN} = 10$ V, $R_g = 2.5 \Omega$	-	20	30	ns	
Fall Time ^c	t _f		-	12	20		
Source-Drain Diode Ratings and Cha	racteristics (T _C = 25 °C)					
Pulsed Current	I _{SM}		-	-	100	А	
Diode Forward Voltage ^b	V _{SD}	$I_F = 40 \text{ A}, V_{GS} = 0 \text{ V}$	-	1.2	1.5	V	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 50 A, dl/dt = 100 A/µs	-	25	70	ns	

Notes

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

c. Independent of operating temperature.

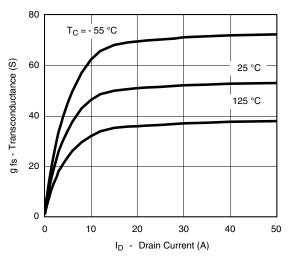
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



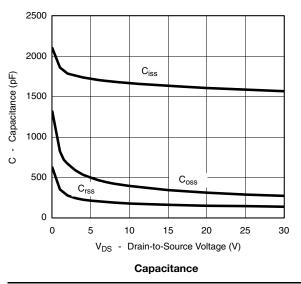
TYPICAL CHARACTERISTICS (25 °C unless noted)

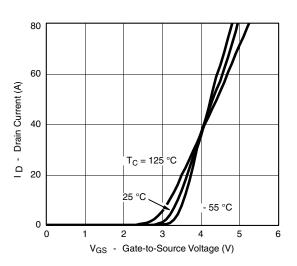
80 10 V thru 5 V V_{GS} 60 I D - Drain Current (A) 40 4 V 20 3 V 0 0 2 3 4 5 1 V_{DS} - Drain-to-Source Voltage (V)

Output Characteristics

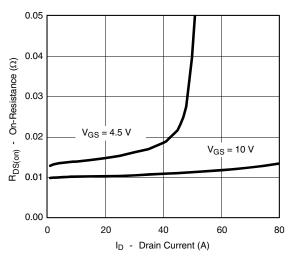


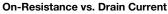


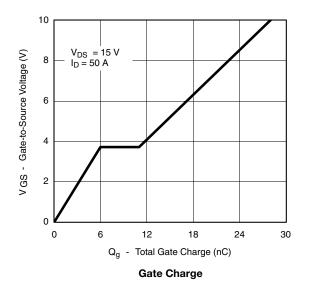




Transfer Characteristics







S15-1807-Rev. A, 10-Aug-15

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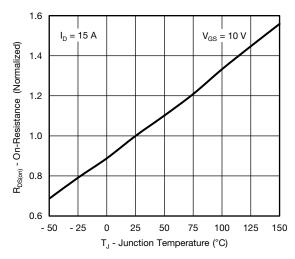
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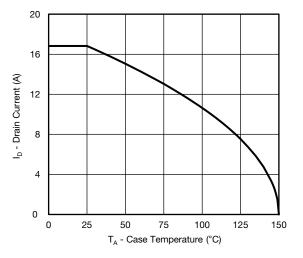
SUD50N03-12P-GE3

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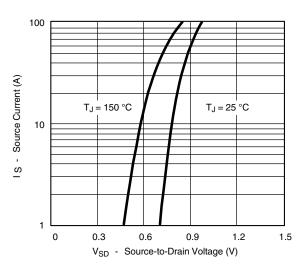
THERMAL RATINGS



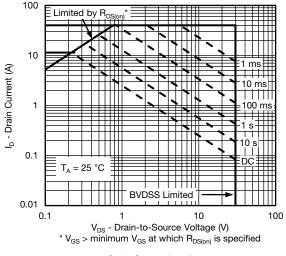
On-Resistance vs. Junction Temperature



Maximum Drain Current vs. Ambient Temperature



Source-Drain Diode Forward Voltage

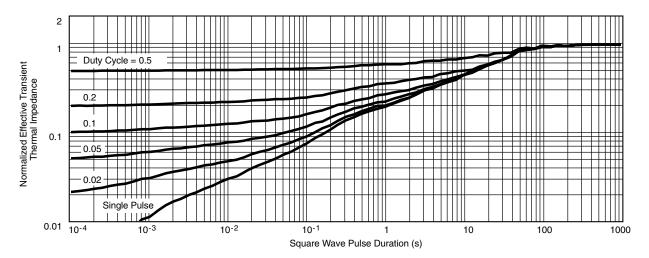


Safe Operating Area

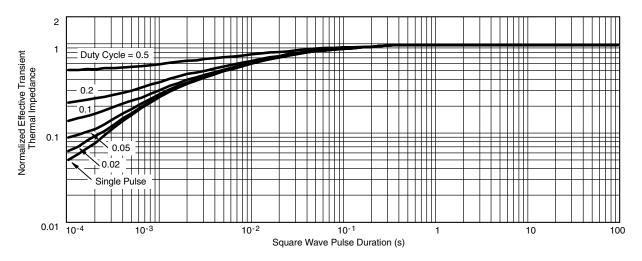


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THERMAL RATINGS

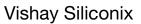


Normalized Thermal Transient Impedance, Junction-to-Ambient



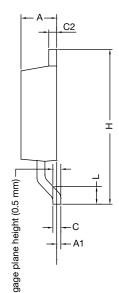
Normalized Thermal Transient Impedance, Junction-to-Case

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Е b3 Ľ Δ LC, b2 e1 Б



TO-252AA Case Outline

	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	4.10	-	0.161	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56	4.56 BSC		0.180 BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.01	1.52	0.040	0.060	
ECN: T16- DWG: 534	0236-Rev. P, ⁻ 7	16-May-16	•		

Notes

• Dimension L3 is for reference only.

b

E1

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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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